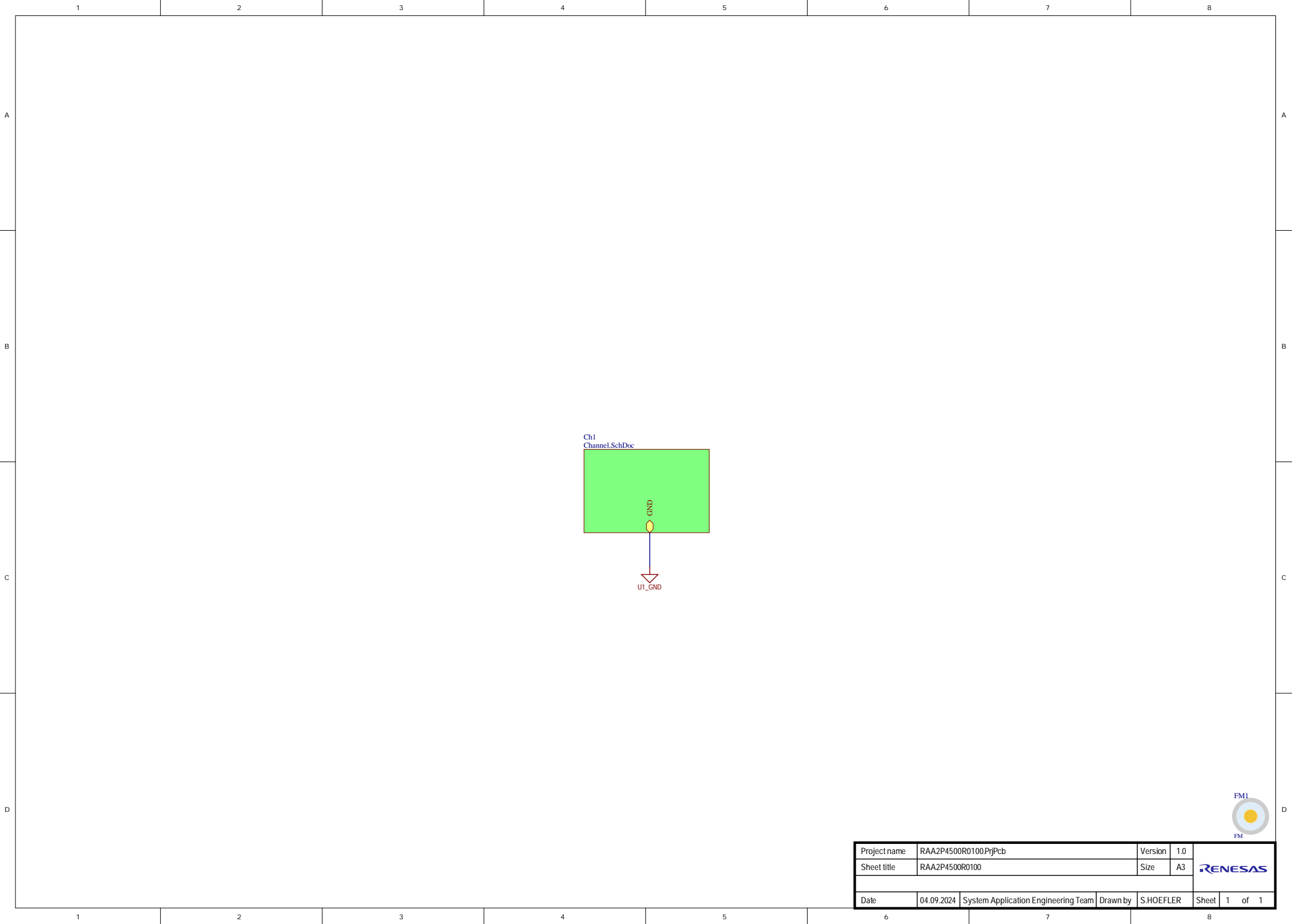





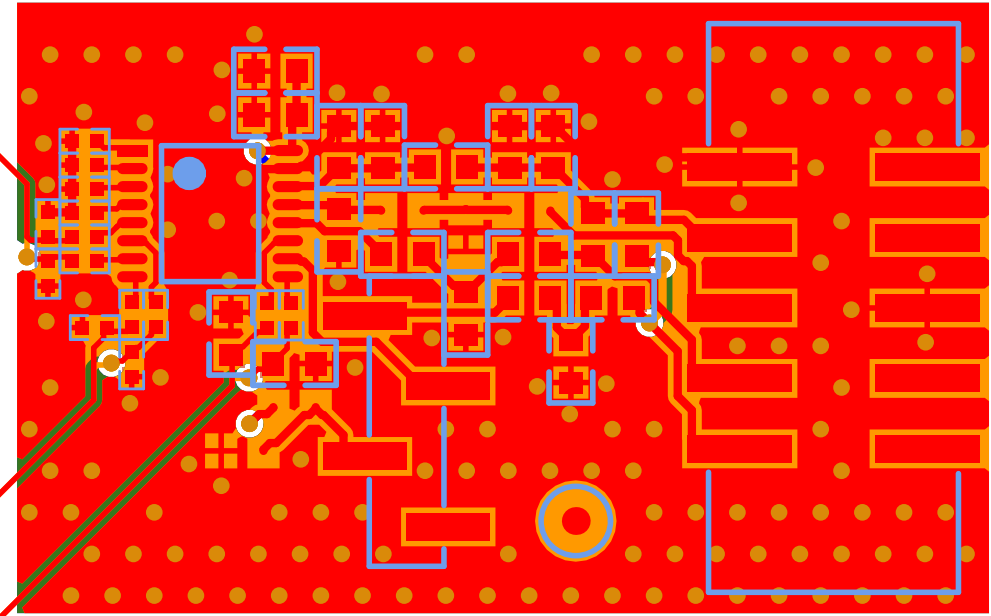
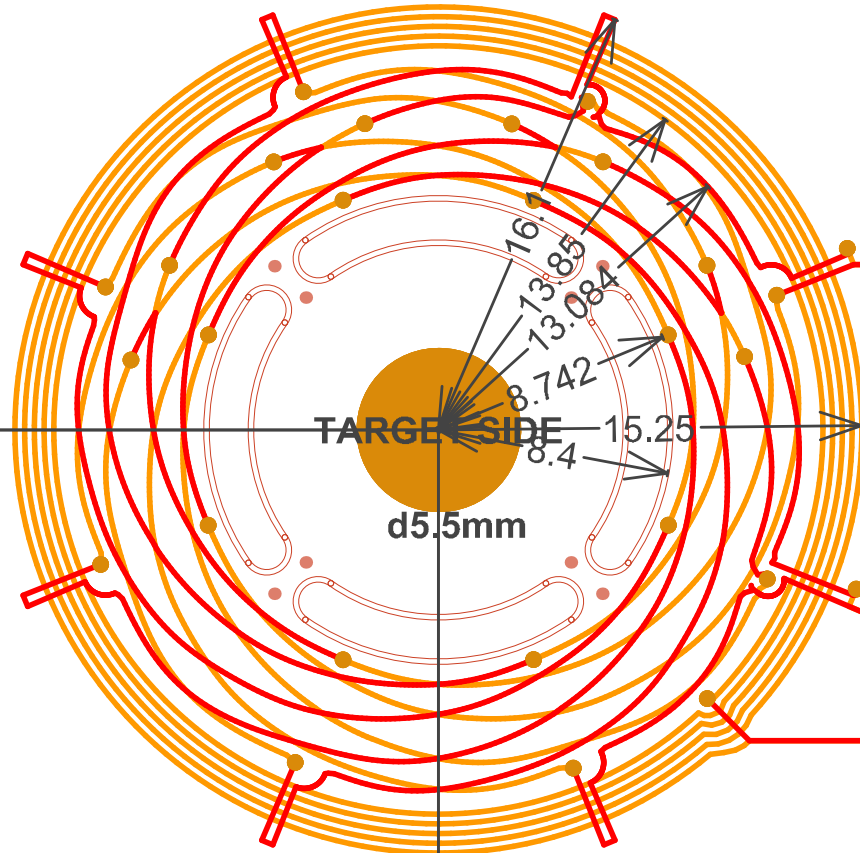
RAA2P4500R0100

| | |
|----------|---|
| Date: | 04.09.2024 |
| Project: | RAA2P4500R0100.PrjPcb |
| Version | 1.0 |
| Content: | Schematic Sensor PCB Layout Sensor PCB Placement Sensor PCB 3D Model PCB Manufacturing Requirements Sensor PCB Layer View Sensor PCB Layer Stack Bill Of Materials Target PCB Layout Target PCB 3D Model |



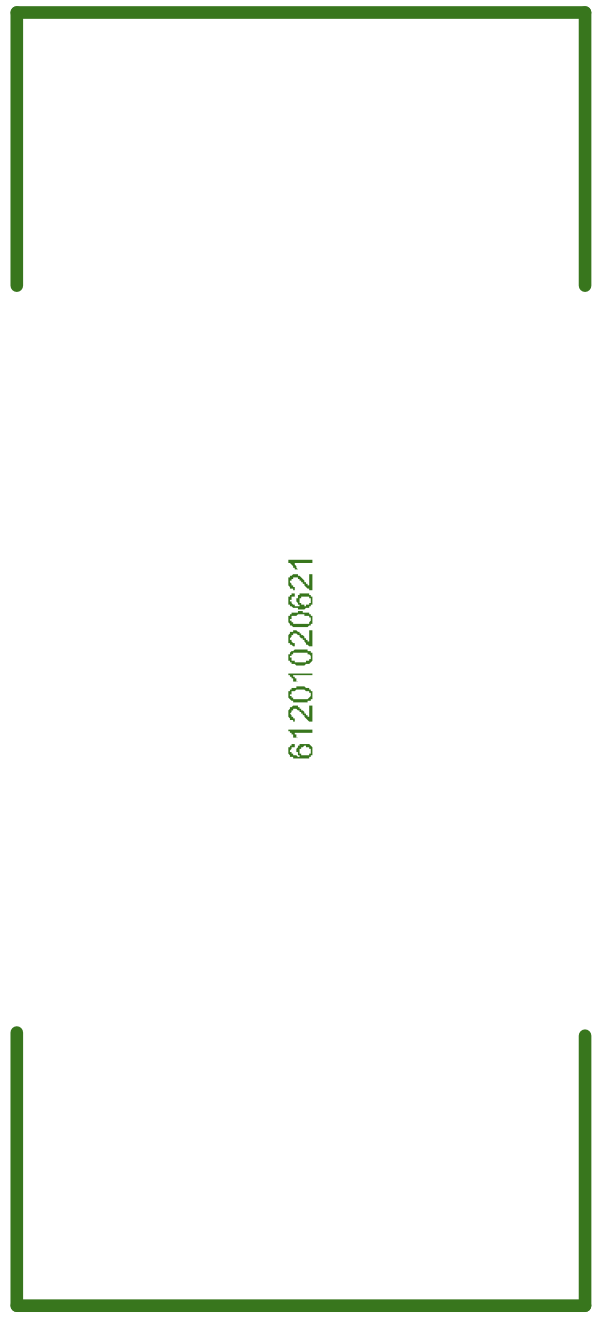
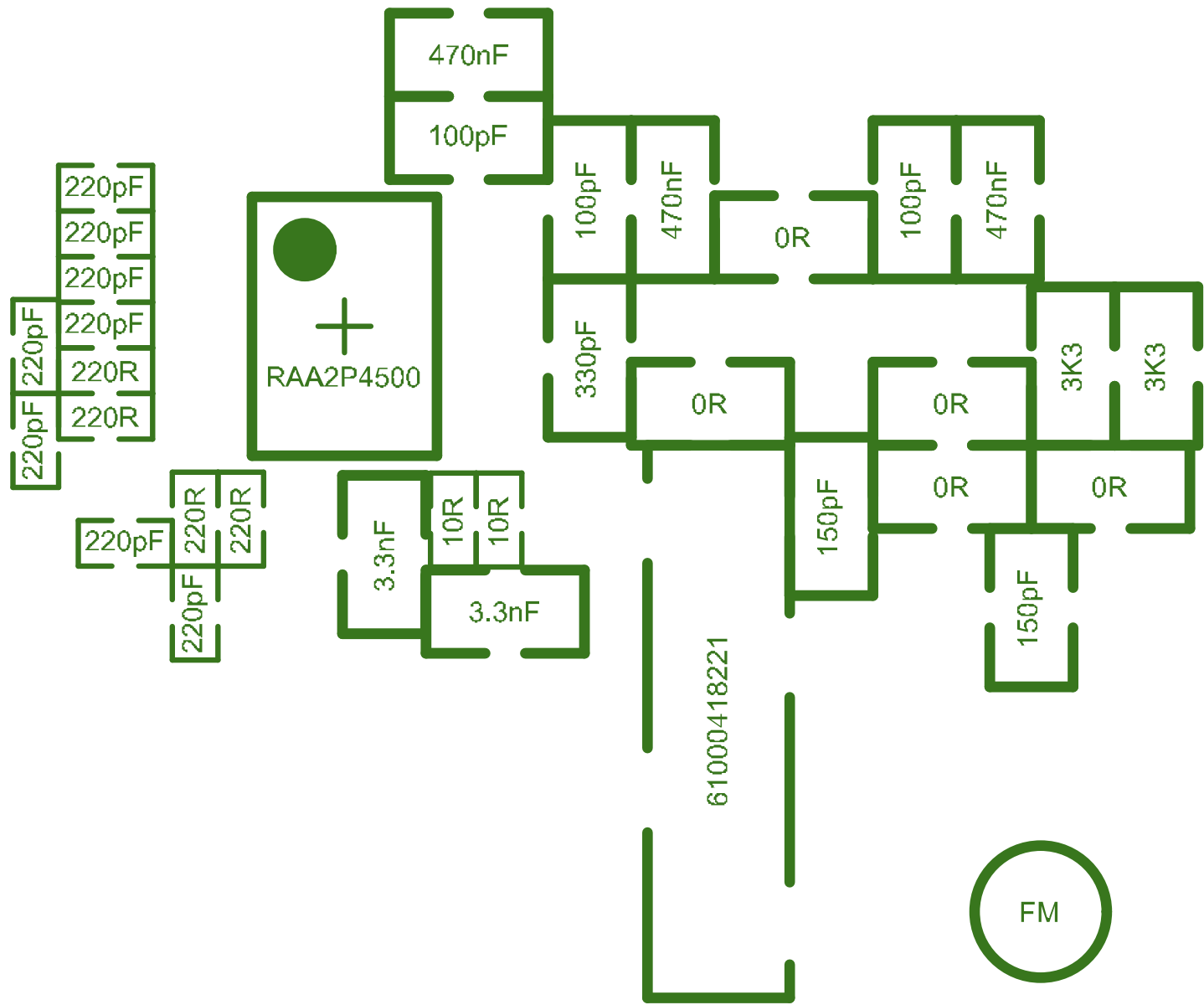
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|--------------|-----------------------|-------------------------------------|--|----------|-----------|---|--------|
| Project name | RAA2P4500R0100.PrfPcb | | | Version | 1.0 |  | |
| Sheet title | RAA2P4500R0100 | | | Size | A3 | | |
| Date | 04.09.2024 | System Application Engineering Team | | Drawn by | S.HOEFLER | Sheet | 1 of 1 |

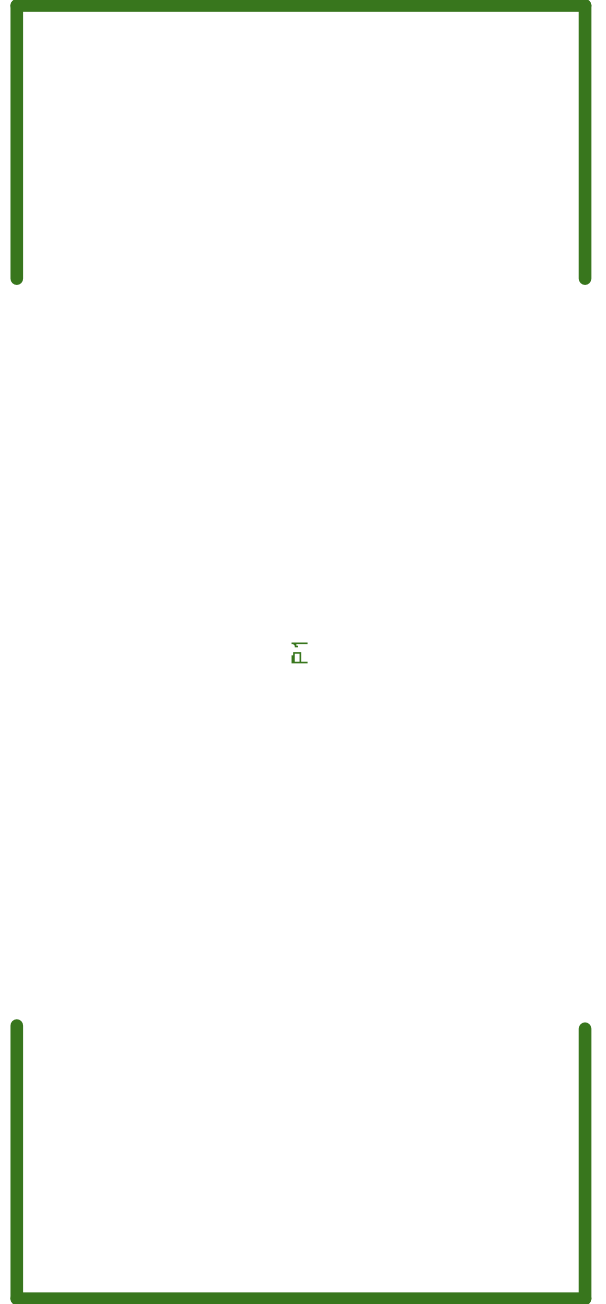
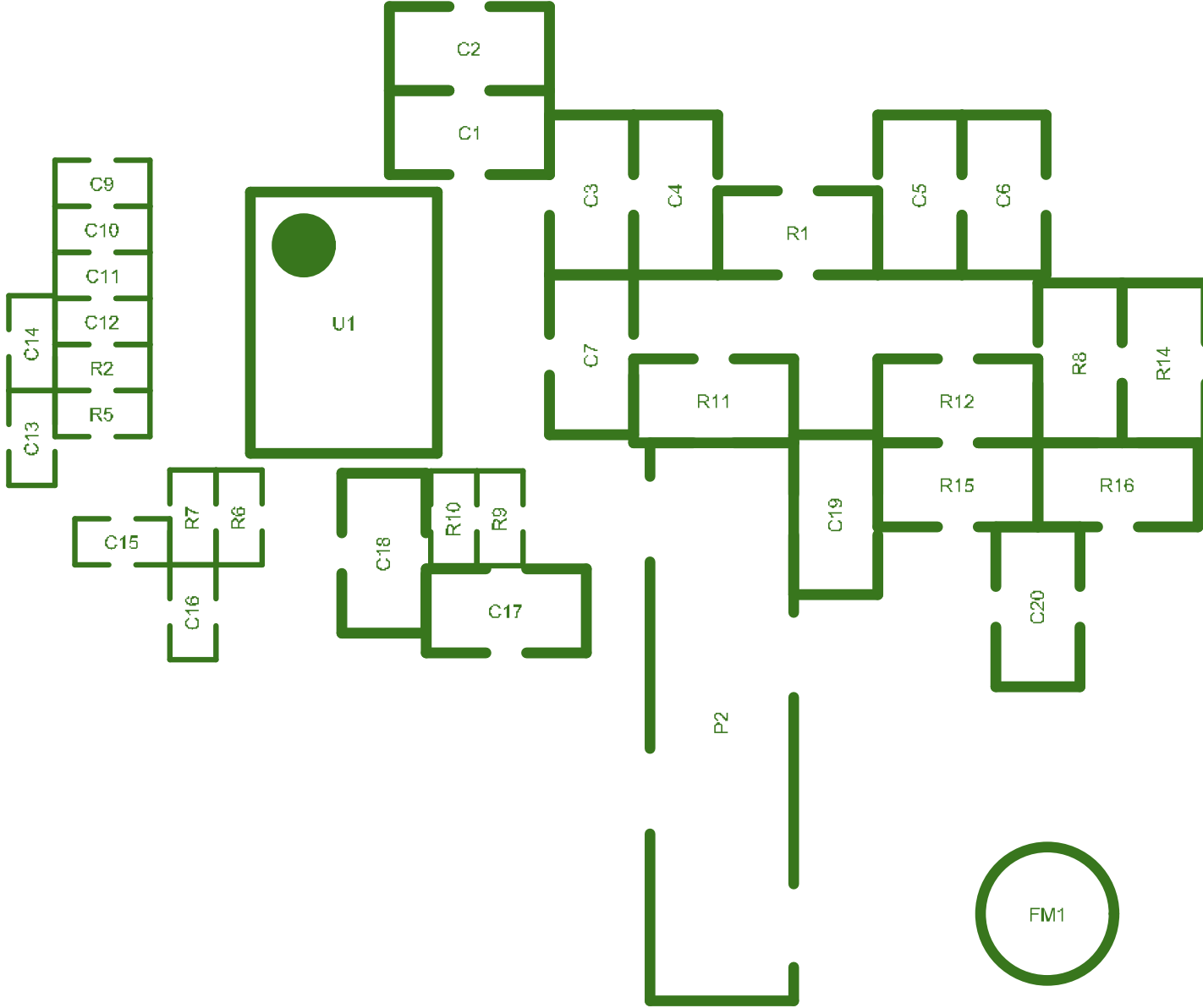
RENESAS



RAA2P4500R0100

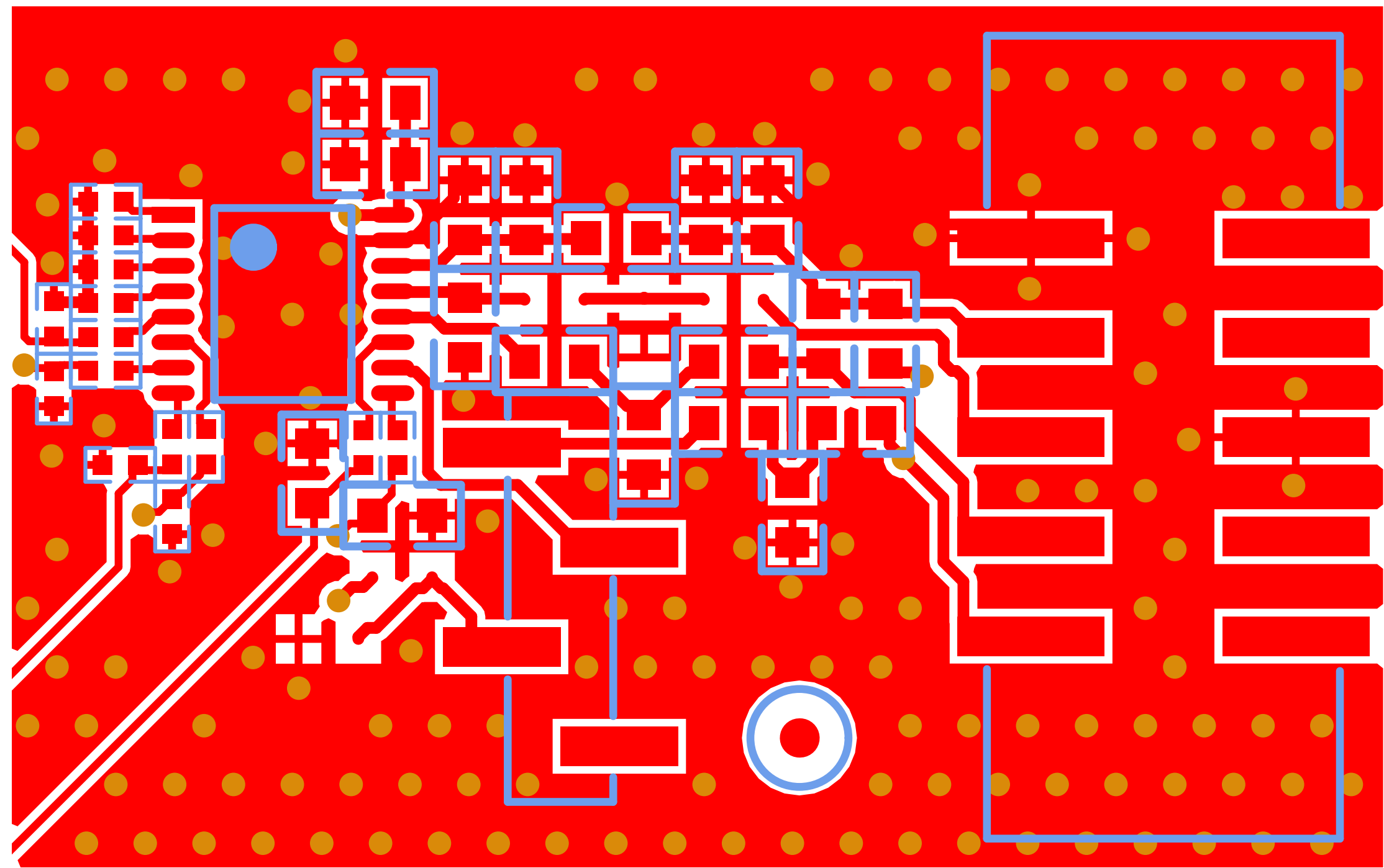
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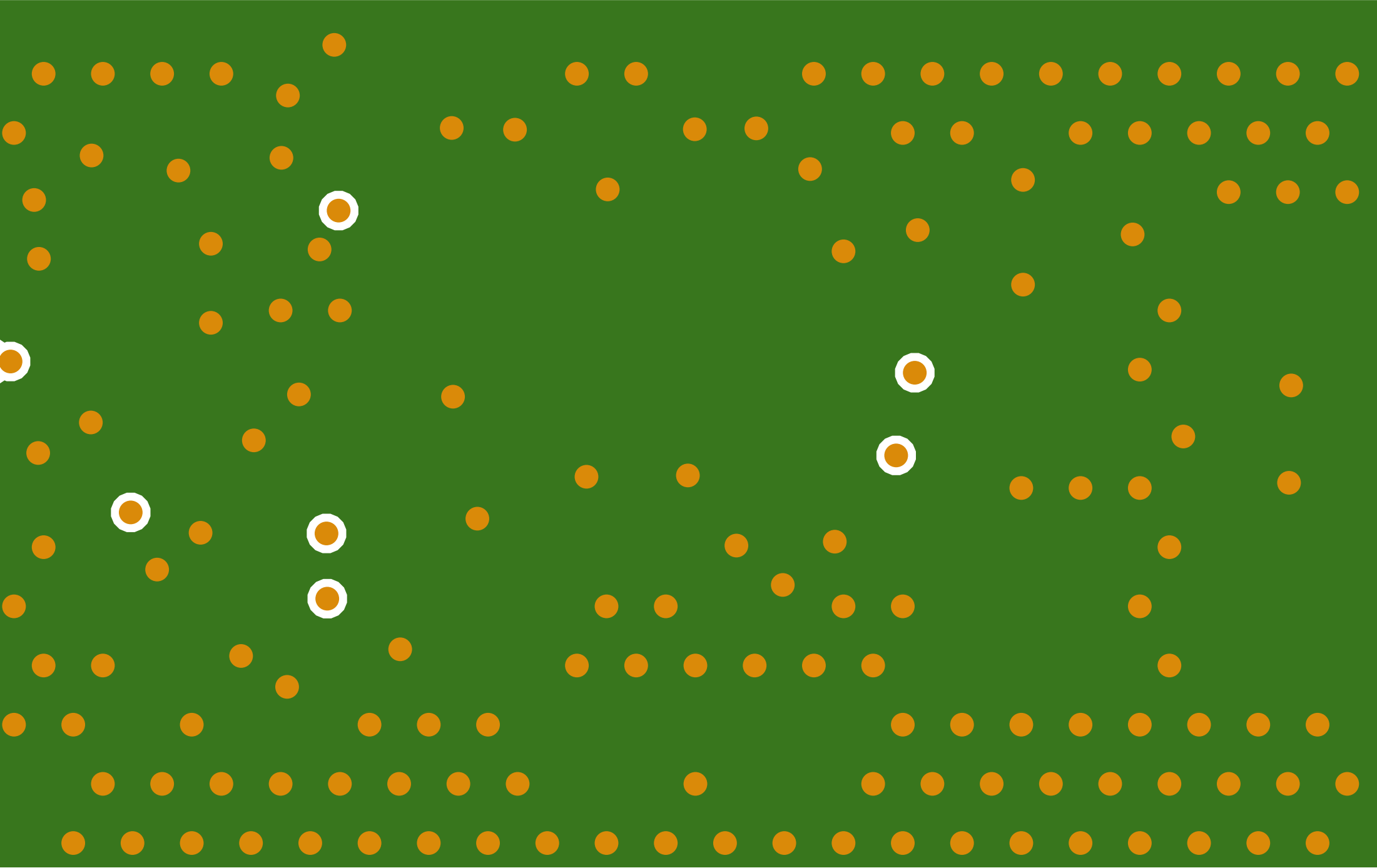


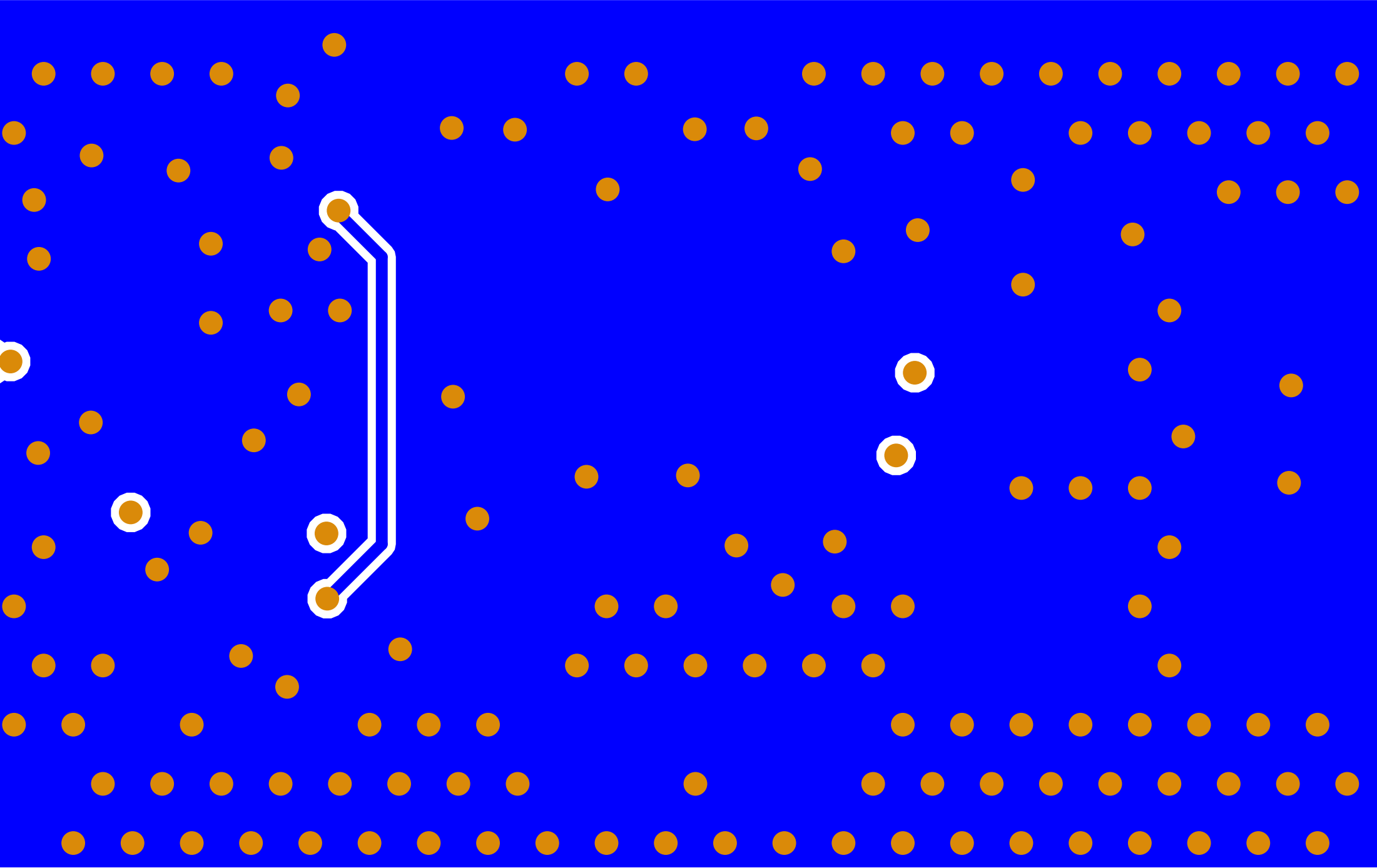
PCB Manufacturing requirements

| | |
|-----------------------------------|--------------------------------|
| Project Name | RAA2P4500R0100 |
| Number of copper layers | 4 |
| PCB Base material | FR-4 |
| Final PCB Thickness | 1.6 mm (62.9 mil) \pm 10% |
| Thickness of copper coating | 35um |
| Final cover | ENIG |
| Minimal copper width | 0.2 mm (7.8 mil) |
| Minimal copper to copper distance | 0.2 mm (7.8 mil) |
| Via hole/pad diameter | 0.3 / 0.6 mm (11.8 / 23.6 mil) |
| Slotted holes | No |
| Panel size | 74 x 40 mm (2913 x 1574 mil) |
| Silk screen color | White on TOP |
| Solder mask color | Blue |
| Blind Vias | No |




















Board Stack Report

| Stack Up | | Layer Stack | | |
|----------|---|----------------|---------------|-----------|
| Layer | Board Layer Stack | Name | Material | Thickness |
| 1 |  | Top Overlay | | 0mm |
| 2 |  | Top Solder | Solder Resist | 0.01mm |
| 3 |  | Top Layer | | 0.035mm |
| 4 |  | Dielectric 1 | FR-4 | 0.32mm |
| 5 |  | Inner1 | | 0.035mm |
| 6 |  | Dielectric2 | FR-4 | 0.8mm |
| 7 |  | Inner2 | | 0.035mm |
| 8 |  | Dielectric3 | FR-4 | 0.32mm |
| 9 |  | Bottom Layer | | 0.035mm |
| 10 |  | Bottom Solder | Solder Resist | 0.01mm |
| 11 |  | Bottom Overlay | | 0mm |
| | Height : 1.6mm | | | |

| Designator | Value | Quantity | Footprint | Description |
|---------------------------------------|--------------------|----------|-------------|--|
| C9, C10, C11, C12, C13, C14, C15, C16 | 220pF | 8 | C0402 3D | Capacitor 0402 220pF X7R |
| R1, R11, R12, R15, R16 | 74279269 3, 33R | 5 | R0603 3D | Resistor 0603 0R |
| R2, R5, R6, R7 | 220R | 4 | R0402 3D | Resistor 0402 220R <5% |
| C1, C3, C5 | 100pF | 3 | C0603 3D | Capacitor 0603 100pF X7R |
| C2, C4, C6 | 470nF | 3 | C0603 3D | Capacitor 0603 470nF X7R |
| C17, C18 | 3.3nF | 2 | C0603 3D | Capacitor 0603 3.3nF NP0 |
| C19, C20 | 150pF | 2 | C0603 3D | Capacitor 0603 150pF X7R |
| R8, R14 | 3K3 | 2 | R0603 3D | Resistor 0603 3K3 <5% |
| R9, R10 | 10R | 2 | R0402 3D | Resistor 0402 10R <5% |
| C7 | 2.2nF | 1 | C0603 3D | Capacitor 0603 330pF X7R |
| P1 | | 1 | 61201020621 | WR-BHD Box Header, Male, pitch 2.54mm, SMT, Straight, 10p |
| P2 | | 1 | 61000418221 | WR-PHD Pin Header, SMT, pitch 2.54mm, Single Row, Vertical, 4p |

